## nexperia

## **Quarterly Reliability Monitoring Results**

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier		User Part Number						
Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		BAS70-07 Part Description						
								Nexperia DHAM
		SMD package						
		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
			TEST Pre- and Post-Stress					
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
# A1	<b>PC</b> Preconditioning	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	810	58300	0		
# B1	<b>HTRB</b> High Temperature Reverse Bias	MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage <sup>[1]</sup>	1000 hours	116	9280	0		
	тс	JESD22-A104						
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	170	13600	0		
≠ A3 alt	<b>AC</b> Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)	96 hours	170	13600	0		
≠ A2 alt	<b>H3TRB</b> High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage <sup>[1], [2]</sup>	1000 hours	170	13600	0		
	IOL	MIL-STD-750 Method 1037 ton = toff, devices powered to insure $\Delta Tj$ =						
# A5	Intermittent Operating Life	100 °C 107 15000 cycles	1000 hours	170	13600	0		
+ C8	<b>RSH</b> Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 s	130	3900	0		
¢ C10	<b>SD</b> Solderability	J-STD-002		363	3630	0		

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia DHAM	Schottky	9280	0	0.46	2.19E+09
	Beneticity	200	5		21152.05

© 2022 Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.

nexperia.com